

19. (New) A semiconductor package, comprising:

- a substrate having an underside;
- a die positioned on said substrate;
- a plurality of signal transferring means electrically connecting said die to said substrate;
- a protective sealant material at least partially formed over said die and said plurality of signal transferring means, said protective sealant material having a top;
- a heat-spreading device operatively associated with said top of said protective sealant material; and
- a plurality of conductive means attached to said underside of said substrate.

20. (New) The semiconductor package of claim 19, further including an adhesive layer between said die and said substrate.

21. (New) The semiconductor package of claim 19 further including a plurality of printed circuits and external circuits, wherein said plurality of conductive means electrically connects said plurality of printed circuits and said external circuits.

22. (New) The semiconductor package of claim 19, wherein said plurality of conductive means includes a plurality of solder balls.

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